Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model **[List multiple models if applicable.]**
HP ProLiant BL685c AMD OPTERON, 2.2G/95W sever blade
HP ProLiant BL685c AMD OPTERON, 2.4G/95W sever blade
HP ProLiant BL685c AMD OPTERON, 2.6G/95W sever blade
HP ProLiant BL685c AMD OPTERON, 2.8G/95W sever blade

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	NA
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	NA
Cathode Ray Tubes (CRT)		NA
Capacitors / condensers (Containing PCB/PCT)		No
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		No
External electrical cables and cords		No
Gas Discharge Lamps		NA
Plastics containing Brominated Flame Retardants		No
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	NA
Components and waste containing asbestos		No
Components, parts and materials containing refractory ceramic fibers		No
Components, parts and materials containing radioactive substances		No

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx driver	T-15
Philips screw driver	#2
Flat head screw driver	Medium

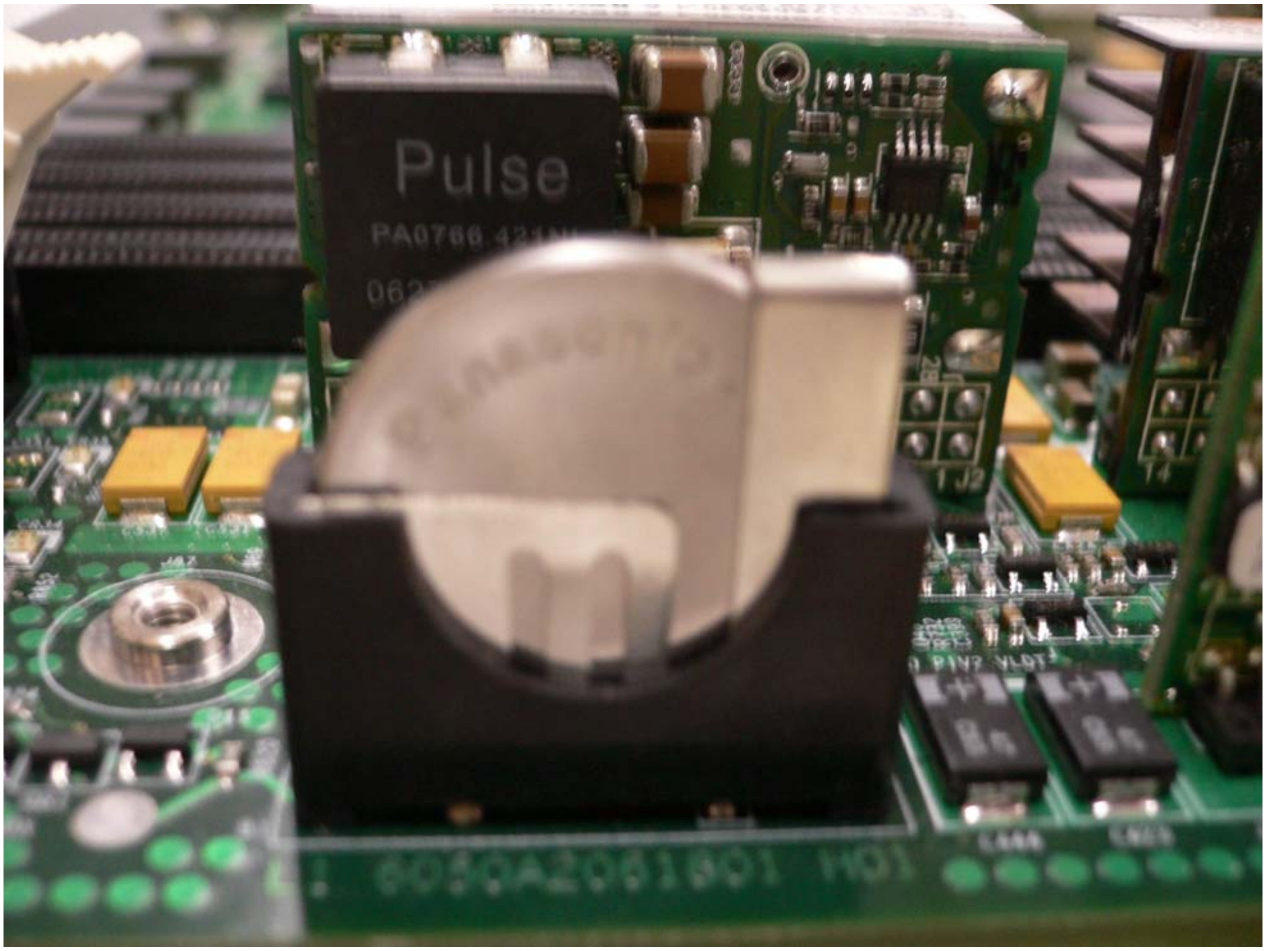
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System Board Battery - Remove the top cover and locate the battery on the system board. Use a medium flat head driver to remove the battery and dispose of properly
2. Battery Backup Write Cache (BBWC) Battery - Remove the top cover and remove the BBWC memory module from the system board. Use a medium flat head screw driver to remove the BBWC battery from the memory module and dispose of properly
3.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 – System Battery Location



Attachment 2.1 – BBWC battery location

Attachment 2.2 – BBWC battery removal

Then remove battery from card